

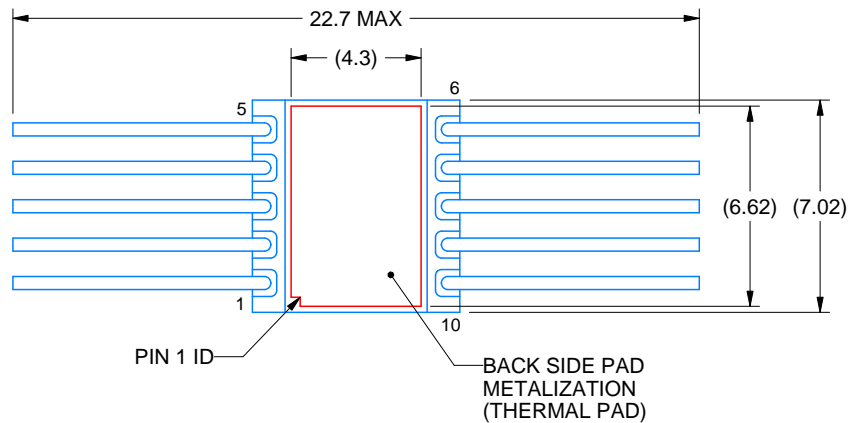
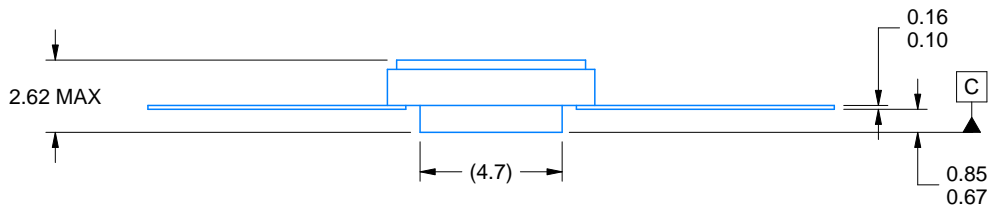
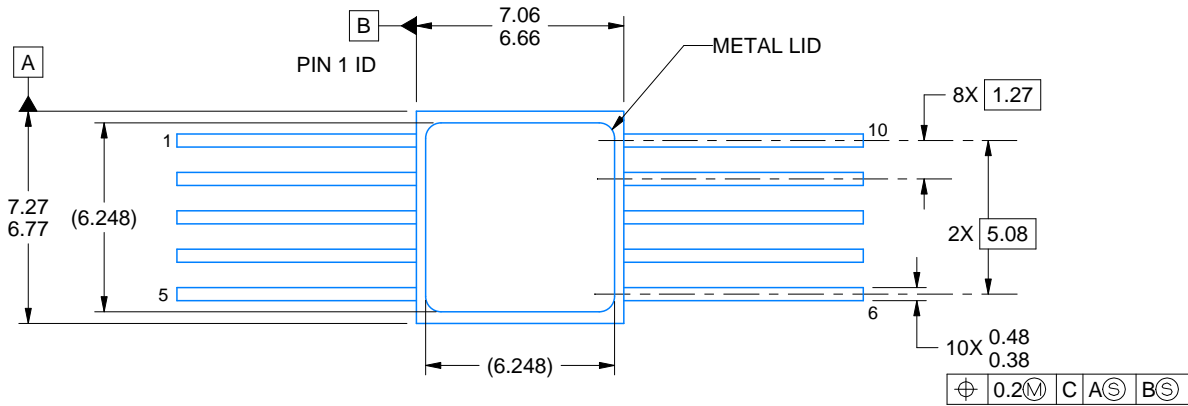


# PACKAGE OUTLINE

## HKU0010A

### CFP - 2.63mm max height

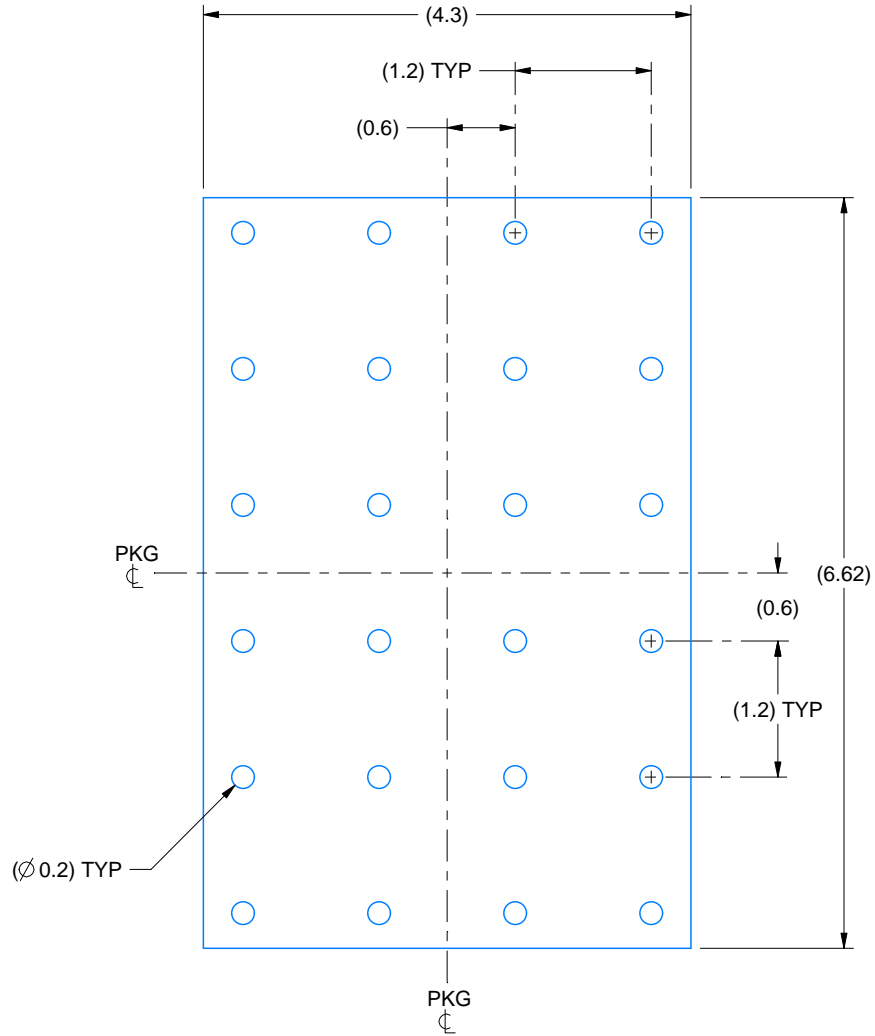
CERAMIC DUAL FLATPACK



4226200/A 09/2020

#### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.
5. This drawing does not comply with MIL STD 1835. Do not use this package for compliant product.
6. Metal lid is connected to back side pad metalization.



HEATSINK LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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